

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-15. (Canceled)

16. (Currently Amended) Microcomponent comprising a hermetically-sealed microcavity, delineated by a cover in which at least one hole is formed, and, on the cover, a sealing layer hermetically sealing the microcavity, the microcomponent comprising, under the sealing layer, a plug covering the hole and a part of the cover over the periphery of the hole, the sealing layer and the plug being formed by distinct materials, wherein the plug is made of ~~a material that is able to undergo creep deformation polymer or of phosphosilicate glass.~~

17. (Canceled)

18. (Currently Amended) Microcomponent according to ~~claim 17~~claim 16, wherein the ~~polymerized material~~polymer is selected from photoresists and polyimide.

19-20. (Canceled)

21. (Previously Presented) Microcomponent according to claim 16, wherein the dimension of the hole is smaller than 5 micrometers.

22. (Previously Presented) Microcomponent according to claim 16, wherein the hole is arranged on the highest part of the microcavity.

23. (Previously Presented) Microcomponent according to claim 16, comprising a plurality of holes.

24. (Previously Presented) Microcomponent according to claim 16, wherein the thickness of the plug is comprised between 2 and 6 micrometers.

25. (Previously Presented) Microcomponent according to claim 16, wherein the plug comprises sloping sides.

26. (Previously Presented) Microcomponent according to claim 16, wherein the plug is non-hermetical.

27. (Previously Presented) Microcomponent according to claim 16, wherein the material of the sealing layer is selected from silicon dioxide, silicon nitride and metals.

28. (Previously Presented) Method for production of a hermetically-sealed microcavity of a microcomponent according to claim 16, successively comprising

- deposition of a sacrificial layer on a substrate,
- deposition of a first layer forming the cover, on the substrate and sacrificial layer,

- etching, in the cover, of at least one hole opening out onto the sacrificial layer,

- removal of the sacrificial layer, via the hole, so as to create the microcavity,
- deposition of the sealing layer, so as to seal the microcavity hermetically,

method comprising deposition of the plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited.

29. (Currently Amended) Method according to claim 28, A Method for production of a hermetically-sealed microcavity of a microcomponent, successively comprising:

- deposition of a sacrificial layer on a substrate;
- deposition of a first layer forming the cover, on the substrate and sacrificial layer;
- etching, in the cover, of at least one hole opening out onto the sacrificial layer;
- removal of the sacrificial layer, via the hole, so as to create the microcavity;

- deposition of the sealing layer, so as to seal the microcavity hermetically;  
the method comprising deposition of a plug covering the hole and a part of the  
cover over the periphery of the hole, after the sacrificial layer has been removed and before  
the sealing layer is deposited;  
wherein, the plug is made of phosphosilicate glass, and the plug is obtained by  
a method selected from solgel methods and cathode sputtering.

30. (Previously Presented) Method according to claim 28, wherein the plug is  
made of a porous material.

31. (Currently Amended) ~~Method according to claim 30, A Method for~~  
production of a hermetically-sealed microcavity of a microcomponent, successively  
comprising:

- deposition of a sacrificial layer on a substrate;  
- deposition of a first layer forming the cover, on the substrate and sacrificial  
layer;  
- etching, in the cover, of at least one hole opening out onto the sacrificial  
layer;  
- removal of the sacrificial layer, via the hole, so as to create the microcavity;  
- deposition of the sealing layer, so as to seal the microcavity hermetically;  
the method comprising deposition of a plug covering the hole and a part of the  
cover over the periphery of the hole, after the sacrificial layer has been removed and before  
the sealing layer is deposited;  
wherein the plug is made of a porous material; and  
wherein, the porous material is a photoresist, and the method comprises a high  
temperature annealing step.

32. (Previously Presented) Method according to claim 30, wherein the method comprises a pumping step of the gas contained in the microcavity, through the porous material, before the sealing layer is deposited.

33. (New) Microcomponent according to claim 16, wherein the microcavity encloses a electromechanical microsystem.